

Certificate TW17/00092

The management system of



KING YUAN ELECTRONICS CO., LTD.

No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.

has been assessed and certified as meeting the requirements of
ISO 45001:2018

For the following activities

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.
3. Provision of Integrated Circuit Testing and Packaging Services

This certificate is valid from 25 November 2023 until 25 November 2026 and remains valid subject to satisfactory surveillance audits.

Issue 7. Certified since 25 November 2020

Certified activities performed by additional sites are listed on subsequent pages.

Authorised by
Stephen Pao
Deputy Director

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KING YUAN ELECTRONICS CO., LTD.

ISO 45001:2018

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| Issue 7 |
| Sites |
| <p>KING YUAN ELECTRONICS CO., LTD. No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p> |
| <p>KING YUAN ELECTRONICS CO., LTD. CHU-NAN BRANCH CHUNG-HUA FACTORY No. 118, Chung-Hua Rd., and No. 8, Lane 228, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p> |
| <p>KING YUAN ELECTRONICS CO., LTD. ASSEMBLY OF SEMICONDUCTOR FACTORY No. 118, Chung-Hua Rd., Chu-Nan, Miao-Li Hsien 350, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p> |
| <p>KING YUAN ELECTRONICS CO., LTD. THIRD FACTORY 3-5 F, No. 81, Sec. 2, Gongdaowu Rd. Hsinchu City 300, Taiwan, R.O.C.</p> <p>1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing. 2. Manufacturing of IC Package and Module Assembly.</p> |



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Certificate TW17/00092, continued

KING YUAN ELECTRONICS CO., LTD.

ISO 45001:2018

KING YUAN ELECTRONICS CO., LTD. SIXTH FACTORY
No. 81, Sec. 2, Gongdaowu Rd. Hsinchu City 300, Taiwan, R.O.C.

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.

KING YUAN ELECTRONICS CO., LTD. TONG-LUO BRANCH
No. 8, Tongke N. Rd., Tong-Luo, Miao-Li Hsien 366, Taiwan, R.O.C.

1. Manufacturing of semiconductor through grinding, dicing, probing, testing and backend processing.
2. Manufacturing of IC Package and Module Assembly.



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